

Nanofinish Advantages

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Nanofinish Process & Test Results Summary



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- Extremely high aging and oxidation resistance, therefore very good solderability after storage, aging, and up to 10 reflows.
 - Better than OSP (Shikoku, Enthone), and better than or at least equal to metallic finishes (ENIG, ImAg, ImSn)
 - Can stand 155°C / 4 hrs like metallic finishes (OSP can not)
- Almost double wetting force compared to established OSP.
- Only slight discoloration during reflow, much less than any OSP. No discoloration after 85/85 test.
- No micro voids (like ImAg, ENIG).
- No “black pad” risk. No copper corrosion (“broken neck”) risk.
- Homogeneous and reliable solder joint. No phase separation.
- No negative issues with shear strength, surface resistance, or e-corrosion.

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- Better light reflection and optical contrast compared to OSP.
 - OSPs make Cu surface darker and brownish.
 - Nanofinish makes it lighter and silvery.
 - Optical control is easier and can be automated.
- Electrical tests can be done after finishing.
- Nanofinish is scratch resistant (no oxidation in scratches).
- At assembly, misprinting can be corrected
 - Solder paste can be removed by organic solvents without removing the Nanofinish layer.
- Compared to ImAg and ImSn – dwell time between assembly steps is not a problem. No deterioration of solderability.
- Significant reduction in energy and raw material demand – most environmental friendly surface finish (for details see [Environmental Impact Estimate.pdf](#))